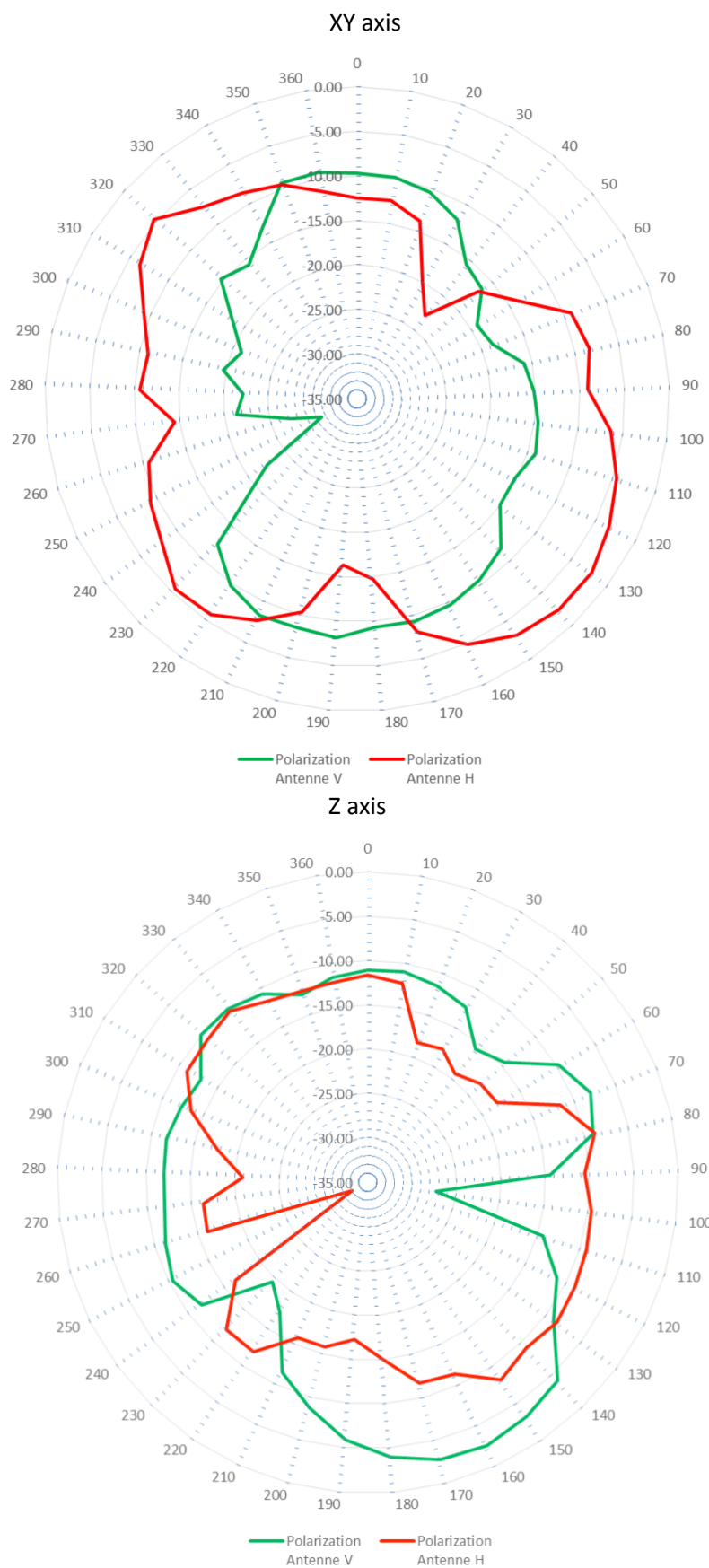


Figure 13. Antenna radiation patterns



8 Thermal characteristics

The thermal characteristics of the STM32WB5MMG are defined below and the constant values are given in Table 4 where:

- Θ_{JA} is the junction-to-ambient thermal resistance (EIA/JESD51-2 and EIA/JESD51-6).
 Θ_{JA} represents the resistance to the heat flows from the chip to ambient air. It is an indicator of package heat dissipation capability. Lower Θ_{JA} means better overall thermal performance and is calculated as follows:

$$\Theta_{JA} = (T_J - T_A) / P_H$$
 where:
 - T_J = junction temperature
 - T_A = ambient temperature
 - P_H = power dissipation.
- Ψ_{JT} is the junction-to-top-center thermal characterization parameter (EIA/JESD51-2 and EIA/JESD51-6).
 Ψ_{JT} is used for estimating the junction temperature by measuring T_T in an actual environment and is calculated as follows:

$$\Psi_{JT} = (T_J - T_T) / P_H$$
 where T_T = temperature at the top-center of the package.
- Θ_{JC} is the junction-to-case thermal resistance.
 Θ_{JC} represents the resistance to the heat flows from the chip to package top case. Θ_{JC} is important when external heat sink is attached on package top and is calculated as follows:

$$\Theta_{JC} = (T_J - T_C) / P_H$$
 where T_C = case temperature attached with a cold plate.
- Θ_{JB} is the junction-to-board thermal resistance (EIA/JESD51-8).
 Θ_{JB} represents the resistance to the heat flows from the chip to PCB. Θ_{JB} is used in compact thermal models for system-level thermal simulation and is calculated as follows:

$$\Theta_{JB} = (T_J - T_B) / P_H$$
 where T_B = board temperature with ring cold plate fixture applied.

Table 4. STM32WB5MMG thermal characteristics

Symbol	$T_J(^{\circ}\text{C})$	$T_T(^{\circ}\text{C})$	$\Psi_{JT}(^{\circ}\text{C/W})$	$\Theta_{JA}(^{\circ}\text{C/W})$	$\Theta_{JB}(^{\circ}\text{C/W})$	$\Theta_{JC}(^{\circ}\text{C/W})$
Value	97.36	96.98	0.38	37.36	24.58	16.21

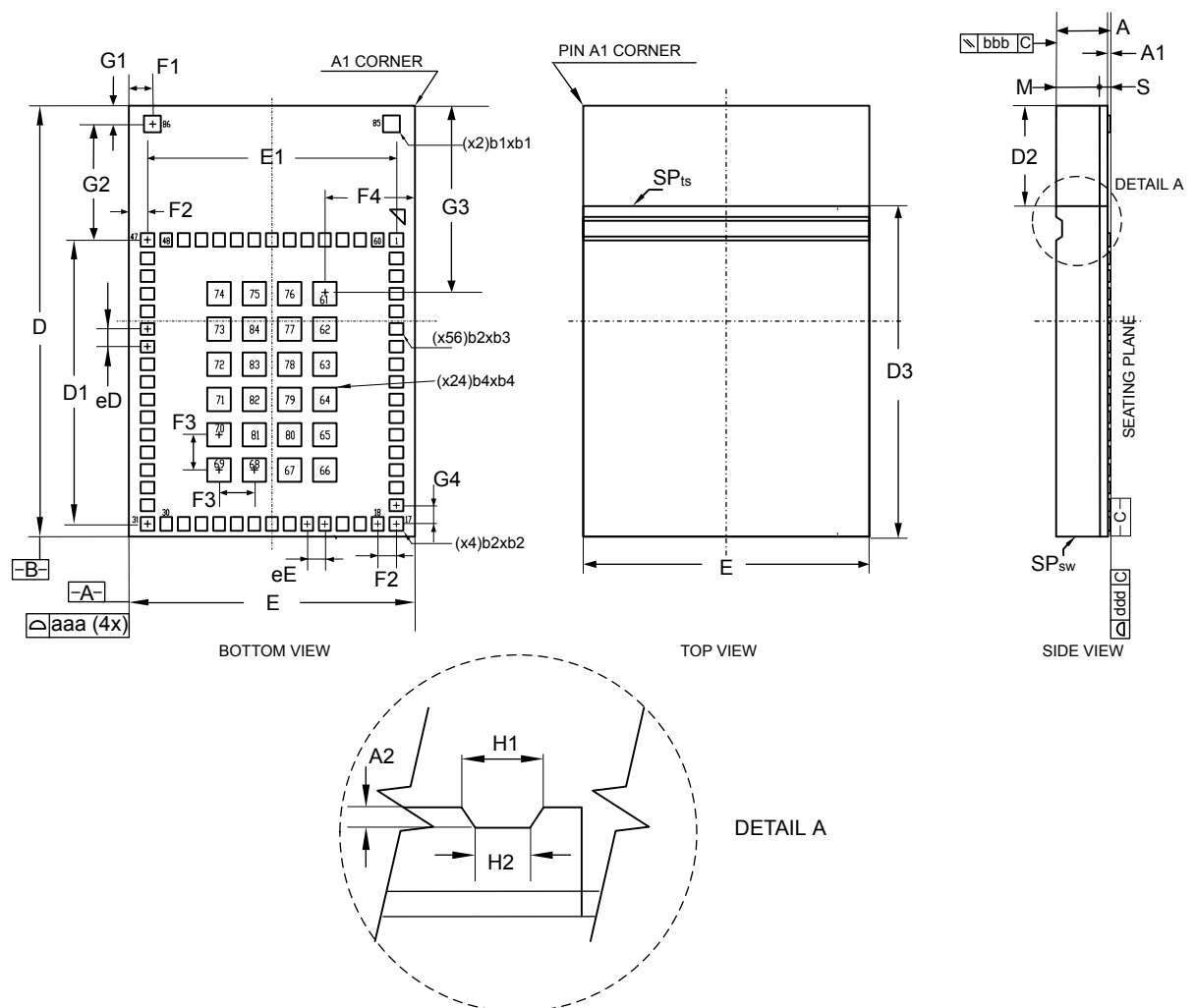
9 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

9.1 SiP-LGA86 package information

This SiP-LGA is a 86 pin, 7.3 x 11mm, system in package land grid array package.

Figure 14. SiP-LGA86 - Outline



1. Drawing is not to scale.

Table 5. SiP-LGA86 - Mechanical data

Symbol	Description	Min	Typ	Max	Unit
A	Total thickness	1.382±0.046			mm
A1	Pre-solder	40±20 ⁽¹⁾			µm
		30±20 ⁽²⁾			
A2	-	0.150			mm
M	Mold thickness	1.100			mm
S	Substrate thickness	0.242			
D	Body length	10925	11.000	11.075	
D1	Lead pitch length	7.250			
D2	-	2.563			
D3	-	8.438			
eD	Lead pitch length	0.450			
E	Body width	7.225	7.300	7.375	
eE	Lead pitch width	0.450			
b1	-	0.430			
b2	-	0.350			
b3	-	0.300			
b4	-	0.600			
F1	-	0.600			
F2	-	0.475			
F3	-	0.900			
F4	-	2.300			
G1	-	0.465			
G2	-	2.960			
G3	-	4.800			
G4	-	0.475			
H1	-	0.600			mm
H2	-	0.400			mm
SP _{ts} ⁽³⁾	Top surface sputter	3	-	6	µm
SP _{sw} ⁽⁴⁾	Side wall sputter	1	-	3	µm
aaa	Package edge tolerance	0.075			mm
bbb	Mold flatness	0.100			
ddd	Coplanarity	0.100			

1. Peripheral pads
2. Inner pads
3. Top surface sputter
4. Side wall sputter

9.2 Board design

For information and recommendations related to board design, landing pads, stencils and the solder reflow profile for LGA packages, refer to *Guidelines for design and board assembly of land grid array packages* (AN 5886).

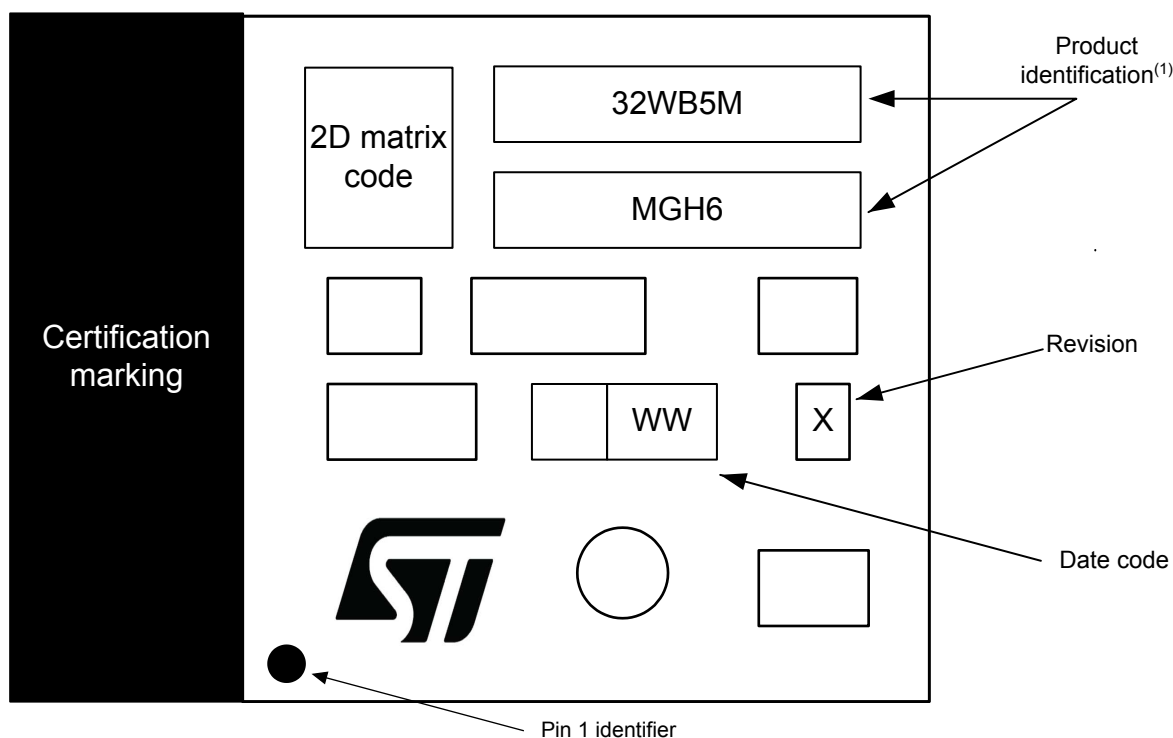
9.3 Device marking for SiP-LGA86

The following figure gives an example of topside marking versus pin 1 position identifier location.

The printed markings may differ depending on the supply chain.

Other optional marking or inset/upset marks, which depend on supply chain operations, are not indicated below.

Figure 15. SiP-LGA86 marking example



DT63781V1

1. Parts marked as "ES", "E" or accompanied by an Engineering Sample notification letter, are not yet qualified and therefore not approved for use in production. ST is not responsible for any consequences resulting from such use. In no event will ST be liable for the customer using any of these engineering samples in production. ST's Quality department must be contacted prior to any decision to use these engineering samples to run a qualification activity.

10 Ordering information

Example:	STM32	WB	5	M	M	G	H	6	TR
Device family	STM32 = Arm-based 32-bit microcontroller								
Product type									
WB = Wireless Bluetooth®									
Device subfamily	5 = STM32WB55, Die 5, full set of features								
Pin count									
M = 86 pins									
Component type	M= module								
Flash memory size									
G = 1 Mbyte									
Package	H = LGA 86 7.3 x 11 mm								
Temperature range									
6 = Industrial temperature range, −40 to 85 °C									
Packing	TR = tape and reel								

Note: For a list of available options (such as speed and package) or for further information on any aspect of this device, contact your nearest ST sales office.

11 Certification

The STM32WB5MMG module certifications status is detailed in the table below:

Table 6. Certification status

Certification		Revision Y	Revision X
Bluetooth Low Energy	RF-PHY	X	X
802.15.4 (Zigbee)	RF-PHY	X	X
EU	RED	X	X
USA	FCC	X	X
Canada	ISED-PCB	X	X
China	SRRC	Pending	X
Japan	JRF	X	X
Korea	KC or MSIP	X	X
Taiwan	NCC	X	X
EU	ROHS	X	X
EU	REACH	X	X
Russia	GOST	X	Pending

The following sections detail some of the module certifications from sample regions.
 All certifications reports are available on STM32WB5MMG page.

11.1 BLE(RF_PHY) certification

The STM32WB5MMG module has obtained BLE RF_PHY certification.
 The module is published under BLE SIG web site.

11.2 CE certification

The STM32WB5MMG module has obtained CE certification.
 The module is provided with CE marking.

Figure 16. CE certification logo



11.3 UKCA certification

The STM32WB5MMG module has obtained UKCA certification.
 The module is provided with UKCA marking.

Figure 17. UKCA certification logo



11.4 FCC certification

The STM32WB5MMG module complies with part 15 of the FCC Rules.
 The FCC ID is YCP-STM32WB5M001 for version Y, and YCP-32WB5MMGH02 for version X.
 The module label includes the corresponding FCC ID.
 The operation is subject to the following two conditions:

- This device may not cause harmful interference
- This device must accept any interference received, including interference that may cause undesired operation.

Note: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation.

Label requirements

If the identification number is not visible when the module is installed inside another device, then the outside of the device into which the module is installed must also display a label referring to the enclosed module. This label must contain the FCC ID that matches the one on the module.

Documentation requirements

The users manual or instruction manual for an intentional or unintentional radiator shall caution the user that changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

Integration requirements

Co-location of this module with other transmitters that operate simultaneously are required to be evaluated using the multi-transmitter procedures.

The host integrator must follow the integration instructions provided in this document and ensure that the composite-system end product complies with the requirements by a technical assessment or evaluation to the rules and to KDB Publication 996369.

The host integrator installing this module into their product must ensure that the final composite product complies with the requirements by a technical assessment or evaluation to the rules, including the transmitter operation and should refer to guidance in KDB 996369.

11.5 ISED certification

The STM32WB5MMG module has been tested and found compliant with the ISED RSS-247 and RSS-Gen rules. The IC ID is 8976A-STM32WB5M01 for version Y and 8976A-32WB5MMGH02 for version X.

This module contains license-exempt transmitter(s) that comply with Innovation, Science and Economic Development Canada's license-exempt RSS(s). Operation is subject to the following two conditions:

- This module may not cause interference
- This module must accept any interference, including interference that may cause undesired operation of the module.

L'émetteur exempt de licence contenu dans le présent appareil est conforme aux CNR d'Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes :

- L'appareil ne doit pas produire de brouillage.
- L'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

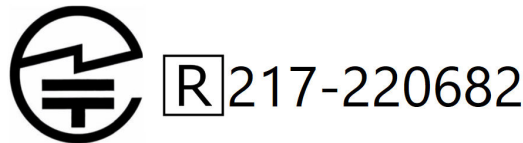
11.6 JRF certification

The STM32WB5MMG is certified in Japan with certification number:

- 005-102490 for rev Y
- 217-220682 for rev X.

The JRF logo is the following:

Figure 18. JRF certification logo



11.7 NCC certification

The STM32WB5MMG rev X is certified in Taiwan with NCC certification number: CCAJ23LP3C40T2.

The STM32WB5MMG rev Y is certified in Taiwan with NCC certification number: CCAN20LP0740T3.

Figure 19. NCC certification logo



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系統廠商應於平台上標示「本□品□含射頻模組：圖片 XXXyyyLPDzzzz-x」字樣

For low-power radio frequency equipment that has obtained certification, companies, firms or users are not allowed to change the frequency, increase the power, or change the characteristics and functions of the original design without approval. The use of low-power radio-frequency equipment must not affect flight safety and interfere with legal communications; if any interference is found, it should be stopped immediately, and it can only be used after improvement to no interference. The aforementioned legal communication refers to radio communication operated in accordance with the provisions of the Telecommunications Management Act. Low-power radio frequency equipment must endure the interference of legal communication or industrial, scientific and medical radio wave radiation electrical equipment. System manufacturers should mark the words "This product contains a radio frequency module: XXXyyyLPDzzzz-x" on the platform.

11.8 **SRRC certification**

The module STM32WB5MMG has received regulatory approval in China (SRRC) with CMIIT ID 2023DP14302.

11.9 **KC certification**

Applicant : STMicroelectronics SAS

Equipment Name: 특정소출력 무선기기(무선데이터통신시스템용 무선기기)

Basic Model Number: STM32WB5MMGH

Certification No.: R-R-2AS-32WB5MMGH002

Manufacturer / Country of Origin: STMicroelectronics SAS / France

Date of manufacture: notation separately

12 Important security notice

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- Certification bodies have the right to evaluate, grant and revoke security certification in relation to ST products. These certification bodies are therefore independently responsible for granting or revoking security certification for an ST product, and ST does not take any responsibility for mistakes, evaluations, assessments, testing, or other activity carried out by the certification body with respect to any ST product.
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- While robust security testing may be done, no level of certification can absolutely guarantee protections against all attacks, including, for example, against advanced attacks which have not been tested for, against new or unidentified forms of attack, or against any form of attack when using an ST product outside of its specification or intended use, or in conjunction with other components or software which are used by customer to create their end product or application. ST is not responsible for resistance against such attacks. As such, regardless of the incorporated security features and/or any information or support that may be provided by ST, each customer is solely responsible for determining if the level of attacks tested for meets their needs, both in relation to the ST product alone and when incorporated into a customer end product or application.
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Revision history

Table 7. Document revision history

Date	Revision	Changes
12-Nov-2020	1	Initial release.
16-Jul-2021	2	Added: - Power supply - SMPS - Clocks - Antenna - Two layer reference board design - BLE(RF_PHY) certification Updated: - Features - Figure 1. STM32WB5MMG module block diagram - Section 3.3: Clocks - Section 5: Pin description - STM32WB5MMG pin/ball definition - Section 6.2.2: Enclosure effects - Figure 8. Four layer reference board schematics - Section 7.4: Antenna radiation patterns and efficiency - Section 9.1: SiP-LGA86 package information - Section 11: Certification - Section 11.1: BLE(RF_PHY) certification
09-Nov-2022	3	Added: - Section 3.1: Versions - Section 3.5: One time programming (OTP) - Figure 8. Four layer reference board schematics for version X - Figure 9. Four layer PCB layout for version X - Figure 10. Two layer reference board schematics for version X - Figure 11. Two layer PCB layout for version X - Section 11.3: UKCA certification - Section 11.9: KC certification - Section 12: Important security notice Updated: - Cerfication images - Bluetooth Bluetooth® Low Energy protocol version support throughout the document - Document title - Section Features - Certification logo representation - Section 1: Introduction - Section 2: Description - Split Section 3: Module overview into a separate section - Section 3.1: Versions - Figure 1. STM32WB5MMG module block diagram - Section 3.2.1: SMPS - Section 3.3: Clocks - Section 5: Pin description - Table 1. STM32WB5MMG pin/ball definition - Section 6.1: Pin recommendations - Section 6.2.4: Sensitive GPIOs - Table 5. SiP-LGA86 - Mechanical data - Figure 8. Four layer reference board schematics for version Y - Figure 10. Four layer PCB layout for version Y - Figure 12. Two layer reference board schematics for version Y - Figure 14. Two layer PCB layout for version Y

Date	Revision	Changes
09-Nov-2022	3	- Section 9.3: Device marking for SiP-LGA86 - Section 9.1: SiP-LGA86 package information - Table 5. SiP-LGA86 - Mechanical data - Section 9.3: Device marking for SiP-LGA86 - Figure 15. SiP-LGA86 marking example - Figure 15. SiP-LGA86 marking example - Section 8: Thermal characteristics - Section 11: Certification - Section 11.4: FCC certification - Section 11.5: ISED certification - Section 11.6: JRF certification - Section 11.7: NCC certification Removed: Solder reflow recommendations section
01-Mar-2023	4	Updated: - Product status - Figure 1. STM32WB5MMG module block diagram - Section 5: Pin description - Figure 2. STM32WB5MMG module pinout: bottom view - Section 6.1: Pin recommendations - Section 6.2.5: Four layer reference board design - Figure 8. Four layer reference board schematics for version X - Section 6.2.6: Two layer reference board design - Figure 10. Two layer reference board schematics for version X - Section 7.4: Antenna radiation patterns and efficiency - Added Figure 13. Antenna radiation patterns - Section 9.2: Board design Removed: "Four layer reference board schematics for version Y" figure "Four layer PCB layout for version Y" figure "Two layer reference board schematics for version Y" figure "Two layer PCB layout for version Y" figure
10-Mar-2023	5	Updated: - Figure 11. Two layer PCB layout for version X - Section 3.2: Power supply - Section 5: Pin description
21-Sep-2023	6	Updated: - Title - Figure 8. Four layer reference board schematics for version X - Figure 10. Two layer reference board schematics for version X - References to DS11929
26-Feb-2024	7	Updated: - Figure 13. Antenna radiation patterns - Table 6. Certification status - Section 11.4: FCC certification - Section 11.5: ISED certification - Section 11.7: NCC certification - Section 11.8: SRRC certification Removed Tape and reel packing

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